

TILE-BASED ROUTING METHOD OF A MULTI-LAYER CIRCUIT BOARD AND RELATED STRUCTURE

Abstract

A routing method for routing a plurality of signal traces out of a plurality of corresponding bumper pads in a multi-layer circuit board. The multi-layer circuit board includes at least a first layer and a second layer. The method includes arranging the plurality of bumper pads based on a plurality of triangle units, routing a plurality of signal traces out of a plurality of corresponding bumper pads of in the first layer, routing a plurality of signal traces out of a plurality of corresponding bumper pads in the second layer not to be vertically parallel with the plurality of signal traces routed in the first layer, and arranging a plurality of shielding traces among the plurality of signal traces in the first layer and in the second layer.